100A, Ultra Low Capacitance TSPD

The NP–SCMC series of Low Capacitance Thyristor Surge Protection Devices (TSPD) protect sensitive electronic equipment from transient overvoltage conditions. Due to their ultra low off–state capacitance (C_0), they offer minimal signal distortion for high speed equipment such as DSL and T1/E1 circuits. The low nominal offstate capacitance translates into the extremely low differential capacitance offering superb linearity with applied voltage or frequency.

The NP-SCMC Series helps designers to comply with the various regulatory standards and recommendations including: GR-1089-CORE, IEC 61000-4-5, ITU K.20/K.21/K.45, IEC 60950, TIA-968-A, FCC Part 68, EN 60950, UL 1950.

Features

- Ultra Low Micro Capacitance
- Low Leakage (Transparent)
- High Surge Current Capabilities
- Precise Turn on Voltages
- Low Voltage Overshoot
- These are Pb-Free Devices

Typical Applications

- xDSL Central Office and Customer Premise
- T1/E
- Other Broadband High Speed Data Transmission Equipment

ELECTRICAL CHARACTERISTICS

	V _{DRM}	V _(BO)	C _O , 2 V, 1 MHz	C _O , 50 V, 1 MHz
Device	V	V	pF (Max)	pF (Max)
NP0640SCMCT3G	±58	± 77	29	13
NP0720SCMCT3G	± 65	±88	29	13
NP0900SCMCT3G	±75	±98	29	13
NP1100SCMCT3G	±90	± 130	29	13
NP1300SCMCT3G	± 120	± 160	29	13
NP1500SCMCT3G	± 140	± 180	29	13
NP1800SCMCT3G	± 170	±220	29	13
NP2100SCMCT3G	± 180	± 240	29	13
NP2300SCMCT3G	± 190	± 260	29	13
NP2600SCMCT3G	± 220	±300	29	13
NP3100SCMCT3G	± 275	±350	29	13
NP3500SCMCT3G	±320	±400	29	13

G in part number indicates RoHS compliance

Other protection voltages are available upon request

Symmetrical Protection – Values the same in both negative and positive excursions

(See V-I Curve on page 3)



ON Semiconductor®

http://onsemi.com

ULTRA LOW CAPACITANCE BIDIRECTIONAL SURFACE MOUNT THYRISTOR 100A, 10x1000μs SURGE





SMB JEDEC DO-214AA CASE 403C

MARKING DIAGRAM



A = Assembly Location

Y = Year WW = Work Week

= Specific Device Code (NPxxx0SCMC)

■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
NPxxx0SCMCT3G	SMB (Pb-Free)	2500 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

SURGE RATINGS

	I _{PPS} A					I _{TSM} A	di/dt		
Waveform (μs)	2x10	8x20	10x160	10x560	10x360	10x1000	5x310	0.1 s 60 Hz	A/μs
Value	500	400	200	120	150	100	200	30	500

MAXIMUM RATINGS ($T_A = 25^{\circ}C$ unless otherwise noted)

Symbol	Rating		Value	Unit	
V_{DRM}	Repetitive peak off-state voltage: Rated maximum	NP0640SCMCT3G	± 58	V	
	(peak) continuous voltage that may be applied in the off-state conditions including all dc and repetitive	NP0720SCMCT3G	± 65		
	alternating voltage components.	NP0900SCMCT3G	± 75		
		NP1100SCMCT3G	±90		
		NP1300SCMCT3G	±120		
		NP1500SCMCT3G	±140		
		NP1800SCMCT3G	± 170		
		NP2100SCMCT3G	± 180		
		NP2300SCMCT3G	±190		
		NP2600SCMCT3G	±220		
		NP3100SCMCT3G	± 275		
		NP3500SCMCT3G	±320		
I _{PPS}	Nonrepetitive peak pulse current: Rated maximum	2x10 μs, GR-1089-CORE	500	Α	
	value of peak impulse pulse current that may be applied.	8x20 μs, IEC-61000-4-5	400		
		10x160 μs, TIA-968-A	200		
		10x560 μs, TIA-968-A	120		
		10x360 μs, GR-1089-CORE	150		
		10x1000 μs, GR-1089-CORE	100		
		5x310 μs, ITU-K.20/K.21/K.45	200		
I _{TSM}	Nonrepetitive peak on-state current: Rated maximum (peak) value of ac power frequency on-state surge current which may be applied for a specified time or number of ac cycles.	0.1s, 50/60 Hz, full sine wave	30	А	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

ELECTRICAL CHARACTERISTICS TABLE ($T_A = 25^{\circ}C$ unless otherwise noted)

Symbol	Rating		Min	Тур	Max	Unit
V _(BO)	O) Breakover voltage: The maximum voltage across the device in or at the NP0640SCMCT3G				±77	V
	ν ΒΟ = 1000 ν, αν/αι = 100 ν/μσ	NP0720SCMCT3G			±88	
		NP0900SCMCT3G			±98	
		NP1100SCMCT3G			± 130	
		NP1300SCMCT3G			±160	
		NP1500SCMCT3G			±180	
		NP1800SCMCT3G			±220	
		NP2100SCMCT3G			±240	
		NP2300SCMCT3G			±260	
		NP2600SCMCT3G			±300	
		NP3100SCMCT3G			±350	
		NP3500SCMCT3G			±400	
I _(BO)	Breakover Current: The instantaneous current flowing at the breakover v	oltage.			800	mA
I _H	Holding Current: The minimum current required to maintain the device in	current required to maintain the device in the on-state.				mA
I _{DRM}	Off-state Current: The dc value of current that results from the applica-	V _D = 50 V			2	μΑ
	tion of the off-state voltage	$V_D = V_{DRM}$			5	
V _T	On–state Voltage: The voltage across the device in the on–state condition $I_T=2.2~\text{A}$ (pk), PW = 300 μs , DC = 2%	across the device in the on-state condition. OC = 2%			4	V
dv/dt	Critical rate of rise of off-state voltage: The maximum rate of rise of volta will not cause switching from the off-state to the on-state. Linear Ramp between 0.1 V _{DRM} and 0.9 V _{DRM}	off-state to the on-state.				kV/μs
di/dt	Critical rate of rise of on-state current: rated value of the rate of rise of cu can withstand without damage.				±500	A/μs
Co	Off-state Capacitance	NP0640SCMCT3G			29	pF
	$f = 1.0 \text{ MHz}, V_d = 1.0 V_{RMS}, V_D = -2 \text{ Vdc}$	NP0720SCMCT3G			29	
		NP0900SCMCT3G			29	
		NP1100SCMCT3G			29	
		NP1300SCMCT3G			29	
		NP1500SCMCT3G			29	
		NP1800SCMCT3G			29	
		NP2100SCMCT3G			29	
		NP2300SCMCT3G			29	
		NP2600SCMCT3G			29	
		NP3100SCMCT3G			29	
		NP3500SCMCT3G			29	

THERMAL CHARACTERISTICS

Symbol	Rating	Value	Unit
T _{STG}	Storage Temperature Range	-65 to +150	°C
TJ	Junction Temperature	-40 to +150	°C
R _{0JA}	Thermal Resistance: Junction-to-Ambient Per EIA/JESD51-3, PCB = FR4 3"x4.5"x0.06" Fan out in a 3x3 inch pattern, 2 oz copper track.	90	°C/W

ELECTRICAL PARAMETER/RATINGS DEFINITIONS

Symbol	Parameter		
V_{DRM}	Repetitive Peak Off-state Voltage		
V _(BO)	Breakover Voltage		
I _{DRM}	Off-state Current		
I _(BO)	Breakover Current		
lн	Holding Current		
V _T	On-state Voltage		
I _T	On-state Current		
I _{TSM}	Nonrepetitive Peak On-state Current		
I _{PPS}	Nonrepetitive Peak Impulse Current		
V _D	Off-state Voltage		
I _D	Off-state Current		

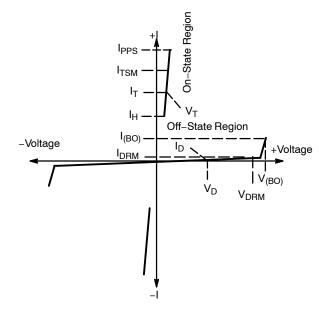


Figure 1. Voltage Current Characteristics of TSPD

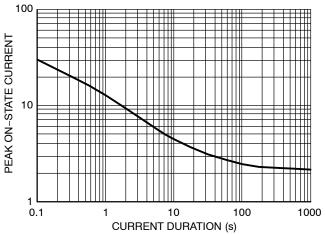


Figure 2. Nonrepetitive On-State Current vs. Time (I_{TSM})

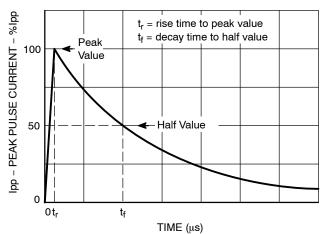


Figure 3. Nonrepetitive On-State Impulse vs. Waveform (I_{PPS})

Detailed Operating Description

The TSPD or <u>Thyristor Surge Protection Device</u> are specialized silicon based overvoltage protectors, used to protect sensitive electronic circuits from damaging overvoltage transient surges caused by induced lightning and powercross conditions.

The TSPD protects by switching to a low on state voltage when the specified protection voltage is exceeded. This is known as a "crowbar" effect. When an overvoltage occurs, the crowbar device changes from a high-impedance to a low-impedance state. This low-impedance state then offers

a path to ground, shunting unwanted surges away from the sensitive circuits.

This crowbar action defines the TSPD's two states of functionality: Open Circuit and Short Circuit.

<u>Open Circuit</u> – The TSPD must remain transparent during normal circuit operation. The device looks like an open across the two wire line.

<u>Short Circuit</u> – When a transient surge fault exceeds the TSPD protection voltage threshold, the devices switches on,

and shorts the transient to ground, safely protecting the circuit.

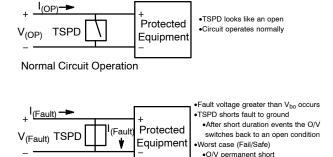


Figure 4. Normal and Fault Conditions

Operation during a Fault

Equipment protected

The electrical characteristics of the TSPD help the user to define the protection threshold for the circuit. During the open circuit condition the device must remain transparent; this is defined by the I_{DRM} . The I_{DRM} should be as low as possible. The typical value is less than 5 μA .

The circuit operating voltage and protection voltage must be understood and considered during circuit design. The $V_{(BO)}$ is the guaranteed maximum voltage that the protected circuit will see, this is also known as the protection voltage. The V_{DRM} is the guaranteed maximum voltage that will keep the TSPD in its normal open circuit state. The TSPD $V_{(BO)}$ is typically a 20–30% higher than the V_{DRM} . Based on these characteristics it is critical to choose devices which have a V_{DRM} higher than the normal circuit operating voltage, and a $V_{(BO)}$ which is less than the failure threshold of the protected equipment circuit. A low on–state voltage V_t allows the TSPD to conduct large amounts of surge current (500 A) in a small package size.

Once a transient surge has passed and the operating voltage and currents have dropped to their normal level the TSPD changes back to its open circuit state.

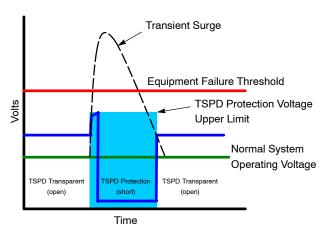


Figure 5. Protection During a Transient Surge

TSPD's are useful in helping designers meet safety and regulatory standards in Telecom equipment including GR-1089-CORE, ITU-K.20, ITU-K.21, ITU-K.45, FCC Part 68, UL1950, and EN 60950.

ON Semiconductor offers a full range of these products in the NP series product line.

DEVICE SELECTION

When selecting a TSPD use the following key selection parameters.

Off-State Voltage V_{DRM}

Choose a TSPD that has an Off-State Voltage greater than the normal system operating voltage. The protector should not operate under these conditions:

Example:

 V_{DRM} should be greater than the peak value of these two components:

$$V_{DRM} > 212 + 48 = 260 V_{DRM}$$

Breakover Voltage V_(BO)

Verify that the TSPD Breakover Voltage is a value less than the peak voltage rating of the circuit it is protecting.

Example: Relay breakdown voltage, SLIC maximum voltage, or coupling capacitor maximum rated voltage.

Peak Pulse Current Ipps

Choose a Peak Pulse current value which will exceed the anticipated surge currents in testing. In some cases the 100 A "C" series device may be needed when little or no series resistance is used. When a series current limiter is used in the circuit a lower current level of "A" or "B" may be used. To determine the peak current divide the maximum surge current by the series resistance.

Hold Current (IH)

The Hold Current must be greater than the maximum system generated current. If it is not then the TSPD will remain in a shorted condition, even after a transient event has passed.

TYPICAL APPLICATIONS

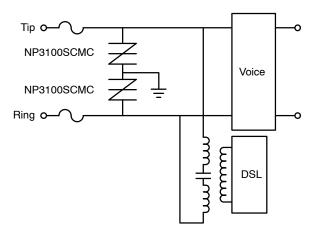


Figure 6. ADSL

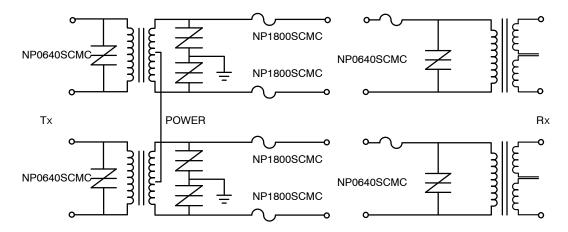
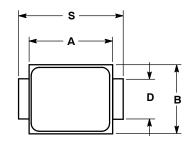
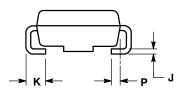


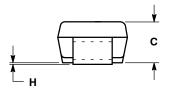
Figure 7. T1/E1

PACKAGE DIMENSIONS

SMB CASE 403C-01 ISSUE A





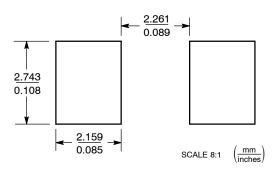


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
- 3. D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.160	0.180	4.06	4.57	
В	0.130	0.150	3.30	3.81	
С	0.075	0.095	1.90	2.41	
D	0.077	0.083	1.96	2.11	
Н	0.0020	0.0060	0.051	0.152	
J	0.006	0.012	0.15	0.30	
K	0.030	0.050	0.76	1.27	
P	0.020 REF		0.51	REF	
S	0.205	0.220	5.21	5.59	

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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